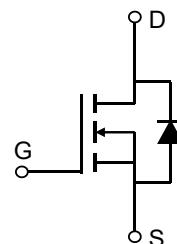


Description

Features

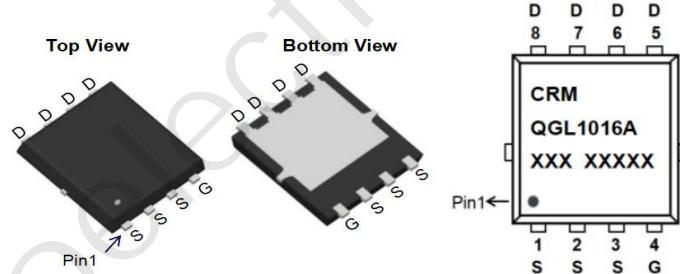
- 100V, 40A
- $R_{DS(ON)}$ Typ = 13mΩ @ V_{GS} = 10V
- $R_{DS(ON)}$ Typ = 16.5mΩ @ V_{GS} = 4.5V
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

| Device | Marking | Package | Outline | Reel Size | Reel (pcs) | Per Carton (pcs) |
|-------------|-------------|----------------|---------|-----------|------------|------------------|
| CRMQGL1016A | CRMQGL1016A | PDFN3.3x3.3-8L | TAPING | 13" | 5000 | 50000 |

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

| Symbol | Parameter | Value | Units |
|-----------------|------------------------------------------------------|------------|-------|
| V_{DS} | Drain-to-Source Voltage | 100 | V |
| V_{GS} | Gate-to-Source Voltage | ± 20 | V |
| I_D | Continuous Drain Current $T_C = 25^\circ\text{C}$ | 40 | A |
| | $T_C = 100^\circ\text{C}$ | 24 | A |
| I_{DM} | Pulsed Drain Current ⁽¹⁾ | 160 | A |
| E_{AS} | Single Pulsed Avalanche Energy ⁽²⁾ | 56 | mJ |
| P_D | Power Dissipation $T_C = 25^\circ\text{C}$ | 48 | W |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 2.6 | °C/W |
| T_J, T_{STG} | Junction & Storage Temperature Range | -55 to 150 | °C |

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------------------------------|----------------------------------------------------------|------------------------------------------------------------|------|------|-----------|------------------|
| Off Characteristics | | | | | | |
| $V_{(\text{BR})\text{DSS}}$ | Drain-Source Breakdown Voltage | $I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$ | 100 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$ | - | - | 1.0 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ | 1.2 | 1.8 | 2.5 | V |
| $R_{\text{DS(ON)}}$ | Static Drain-Source ON-Resistance ⁽³⁾ | $V_{GS} = 10\text{V}, I_D = 15\text{A}$ | - | 13 | 17 | $\text{m}\Omega$ |
| | | $V_{GS} = 4.5\text{V}, I_D = 10\text{A}$ | - | 16.5 | 21.5 | $\text{m}\Omega$ |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | | - | 1130 | - | pF |
| C_{oss} | Output Capacitance | $V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$ | - | 430 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 5.8 | - | pF |
| Q_g | Total Gate Charge | | - | 15.5 | - | nC |
| Q_{gs} | Gate Source Charge | $V_{GS} = 0 \text{ to } 10\text{V}$ | - | 4 | - | nC |
| Q_{gd} | Gate Drain("Miller") Charge | $V_{DS} = 50\text{V}, I_D = 10\text{A}$ | - | 1.9 | - | nC |
| Switching Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-On DelayTime | | - | 4.5 | - | ns |
| t_r | Turn-On Rise Time | $V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$ | - | 5.5 | - | ns |
| $t_{d(off)}$ | Turn-Off DelayTime | $I_D = 10\text{A}, R_{\text{GEN}} = 6\Omega$ | - | 16 | - | ns |
| t_f | Turn-Off Fall Time | | - | 9 | - | ns |
| Drain-Source Diode Characteristics and Max Ratings | | | | | | |
| I_S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 40 | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 160 | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{GS} = 0\text{V}, I_S = 15\text{A}$ | - | - | 1.2 | V |
| trr | Body Diode Reverse Recovery Time | | - | 40 | - | ns |
| Qrr | Body Diode Reverse Recovery Charge | $I_F = 15\text{A}, di/dt = 100\text{A}/\mu\text{s}$ | - | 32 | - | nC |

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $V_G=10\text{V}$, $R_G=25\text{ohm}$, $L=0.5\text{mH}$, $I_{AS}=15\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

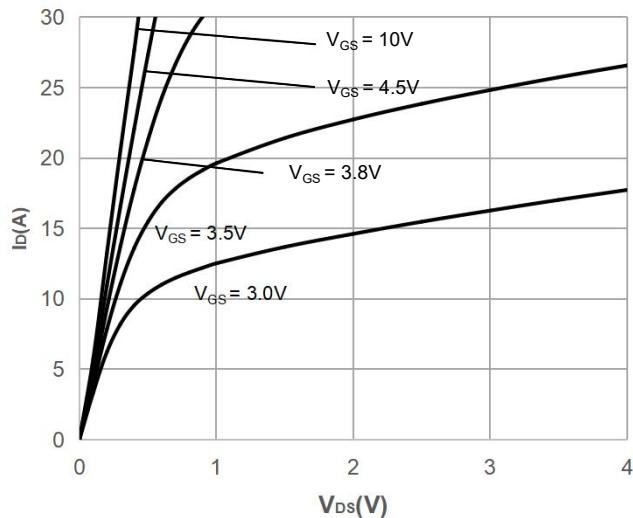


Figure 2: Typical Transfer Characteristics

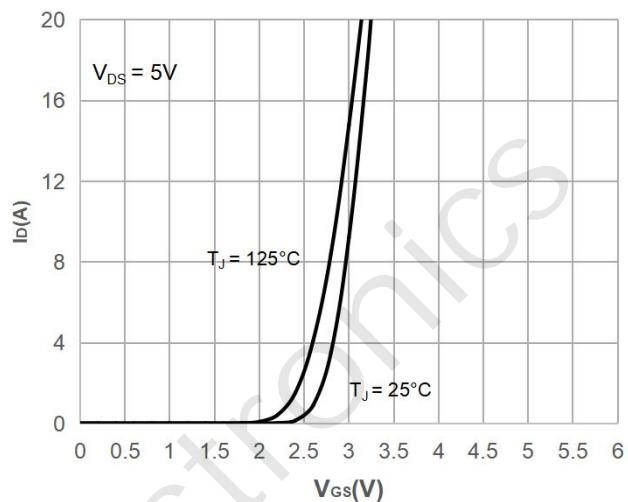


Figure 3: On-resistance vs. Drain Current

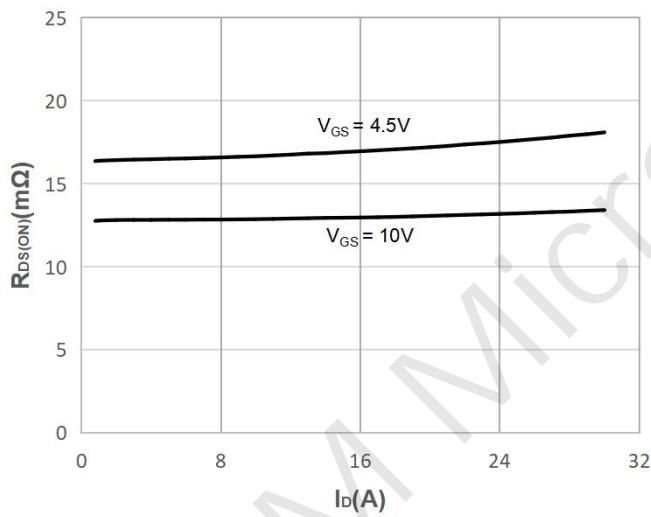


Figure 4: Body Diode Characteristics

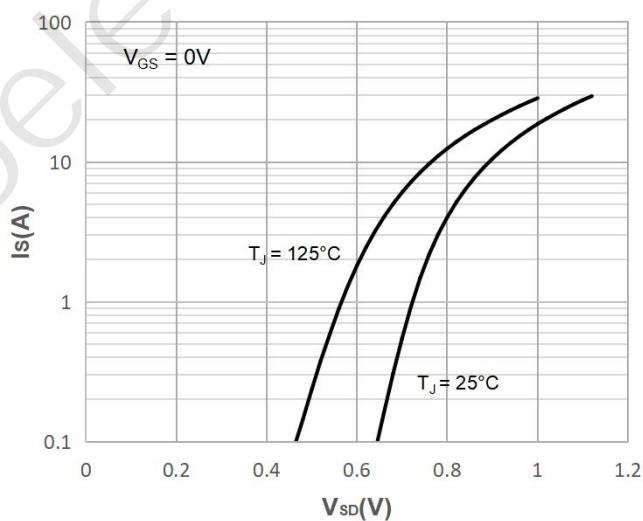


Figure 5: Gate Charge Characteristics

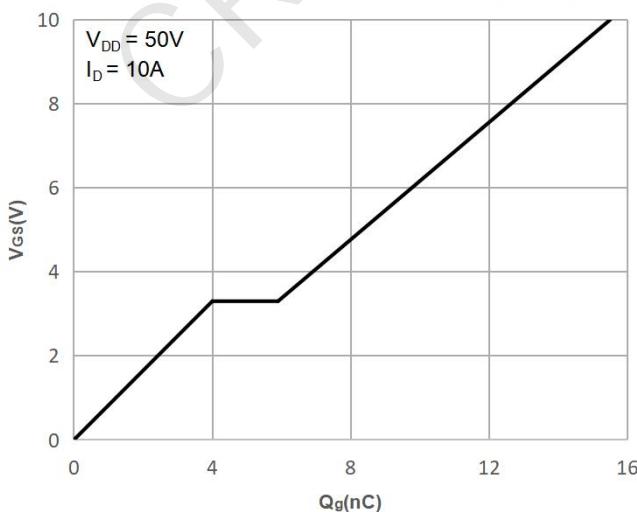
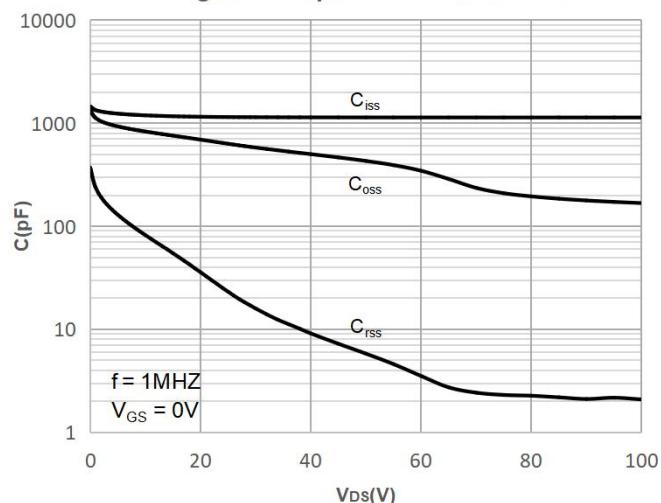


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

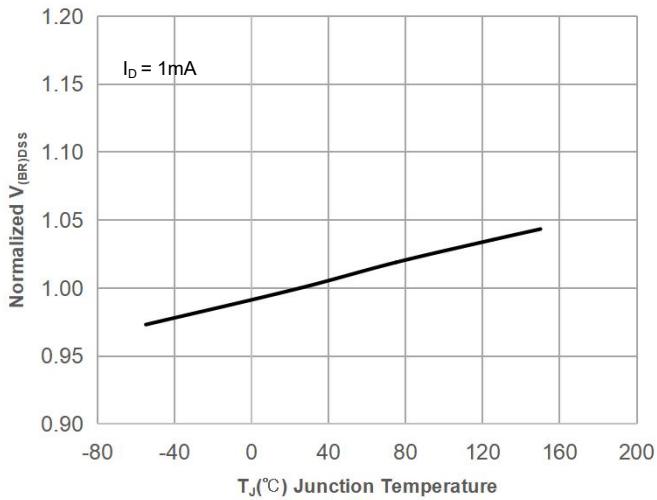


Figure 8: Normalized on Resistance vs. Junction Temperature

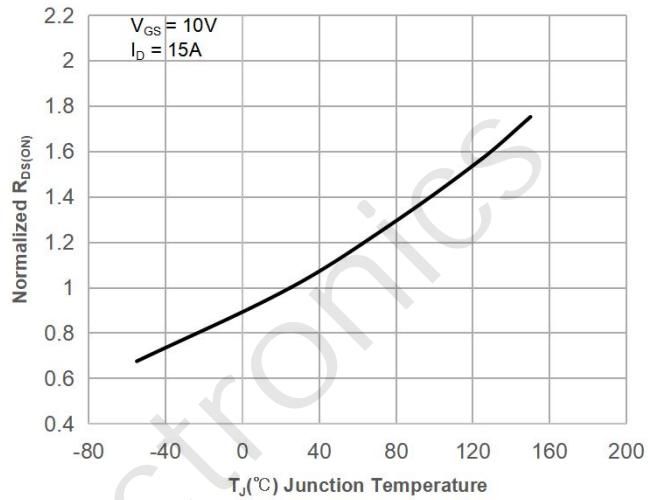


Figure 9: Maximum Safe Operating Area

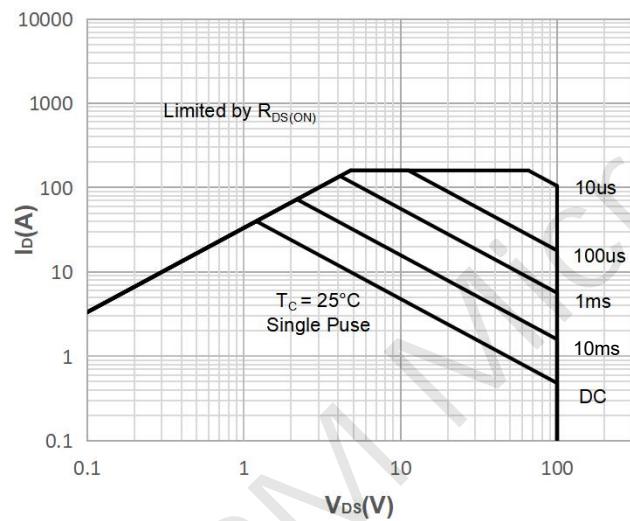


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

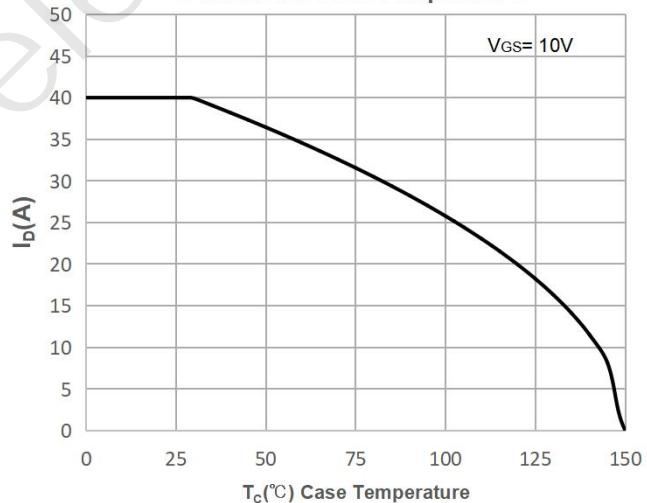


Figure 11: Normalized Maximum Transient Thermal Impedance

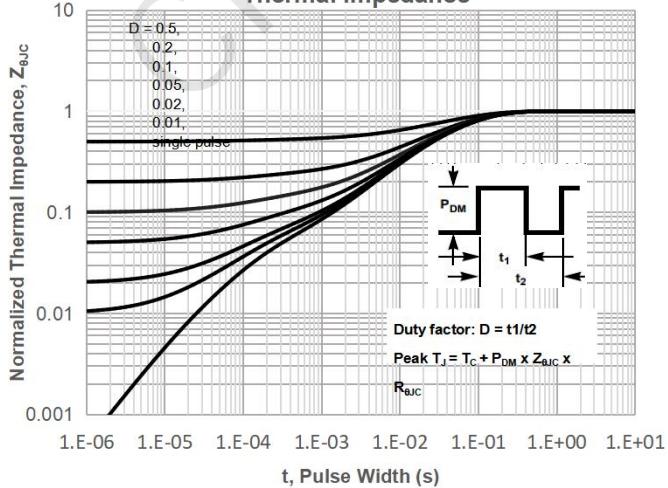
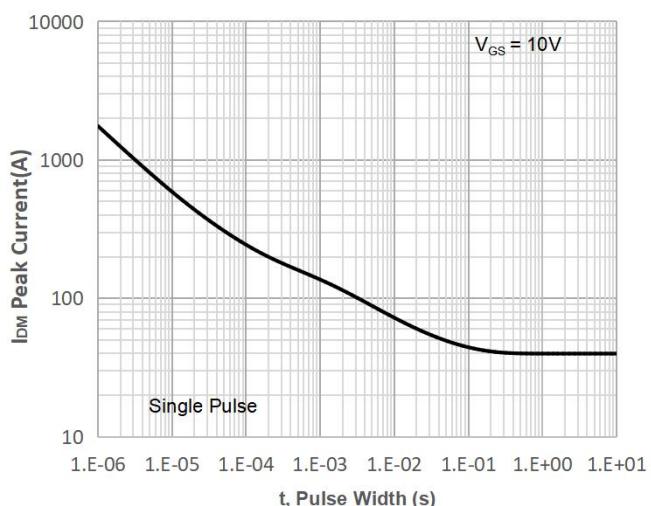


Figure 12: Peak Current Capacity



Test Circuit

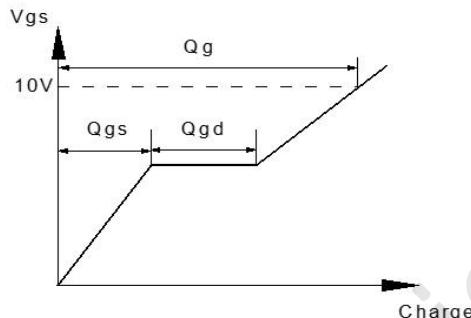
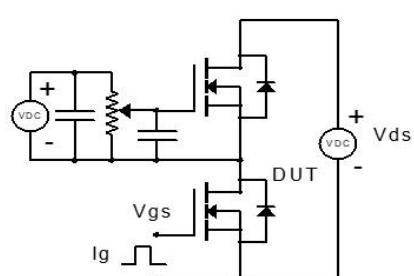


Figure 1: Gate Charge Test Circuit & Waveform

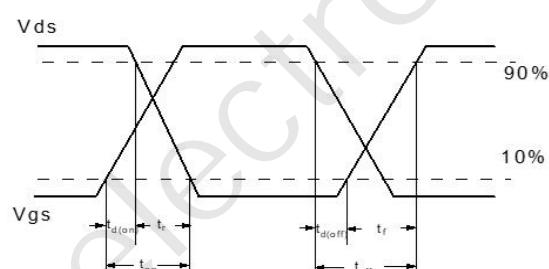
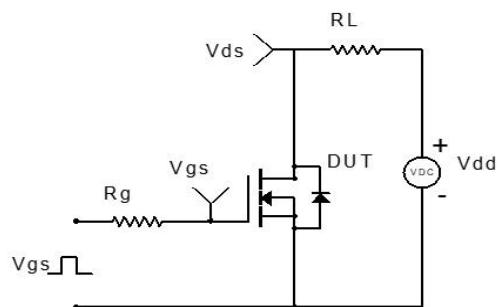


Figure 2: Resistive Switching Test Circuit & Waveform

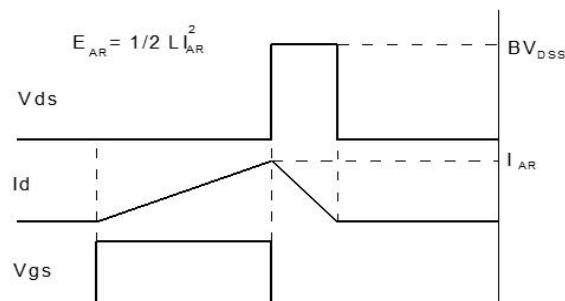
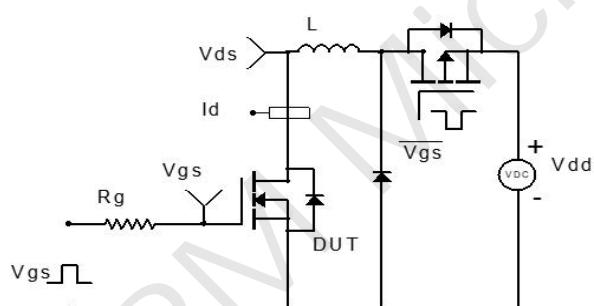


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

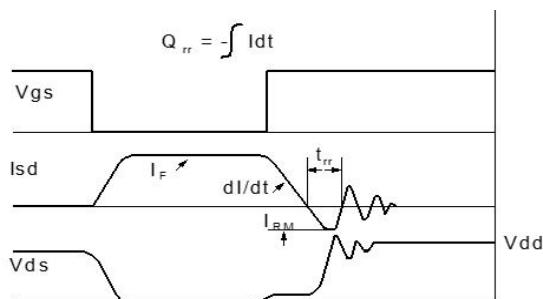
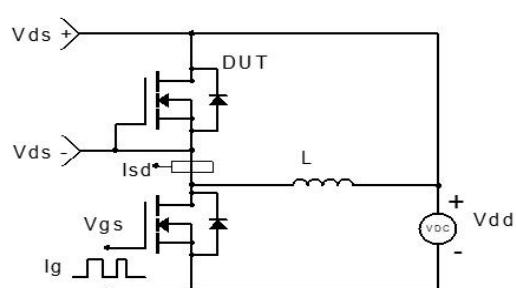
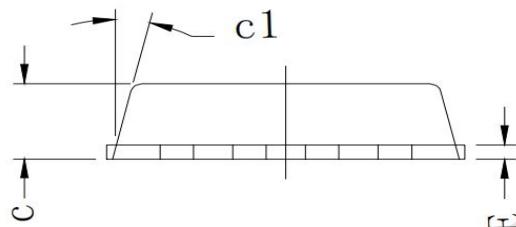
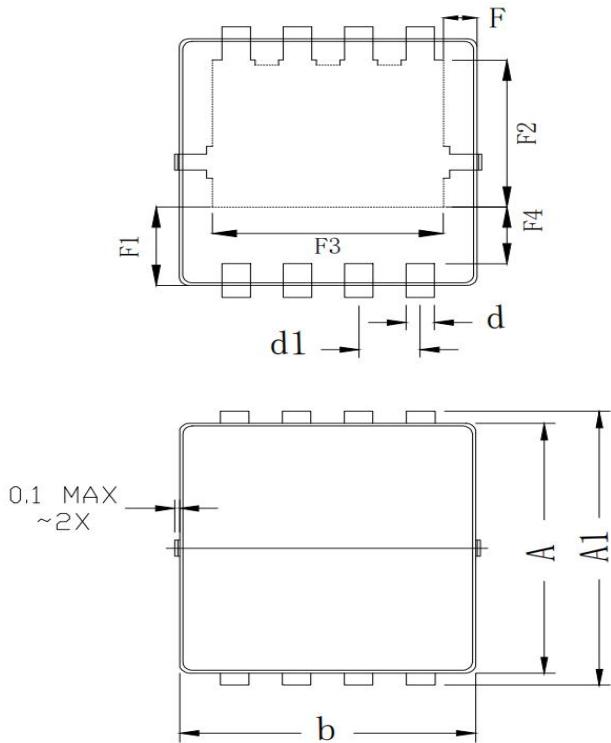


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3.3x3.3-8L)



| COMMON DIMENSION (MM) | | | |
|-----------------------|-----------------|-------|-------|
| PKG | PDFN 3.3x3.3-8L | | |
| SYMBOL | MIN | TYP | MAX |
| A | 3.070 | 3.100 | 3.130 |
| A1 | 3.300 | 3.400 | 3.500 |
| b | 3.070 | 3.100 | 3.130 |
| c | 0.770 | 0.800 | 0.830 |
| c1 | - | 13° | - |
| d | 0.275 | 0.300 | 0.325 |
| d1 | 0.625 | 0.650 | 0.675 |
| E | 0.144 | 0.152 | 0.160 |
| F | 0.300 | 0.325 | 0.350 |
| F1 | 0.960 | 0.985 | 1.010 |
| F2 | 1.775 | 1.800 | 1.825 |
| F3 | 2.425 | 2.450 | 2.475 |
| F4 | 0.660 | 0.685 | 0.710 |

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